

# SOT646-1

plastic thin shrink small outline package; 64 leads; body width 6.1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP64
<b>Package type industry code</b>	TSSOP64
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-153
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-2-2003

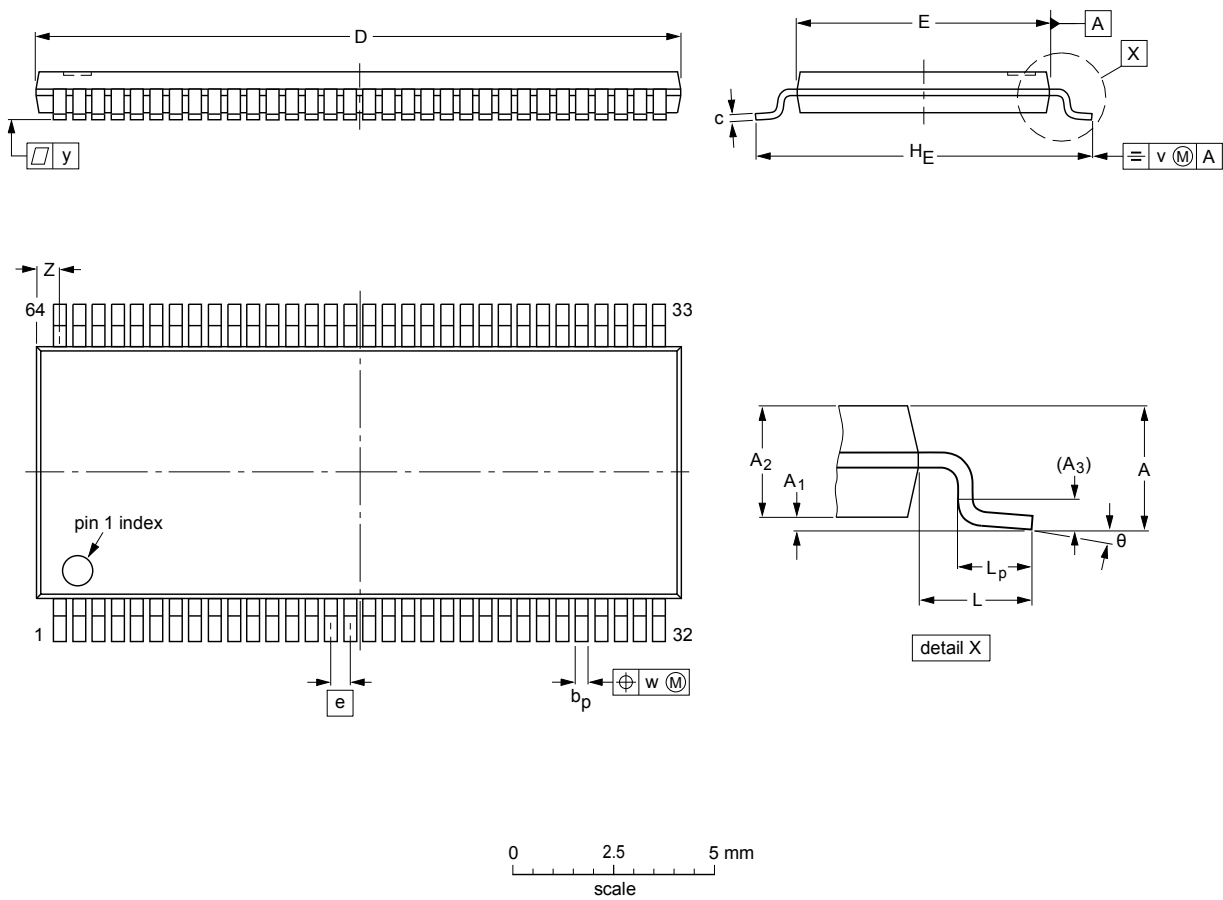
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.9	-	17	17.1	mm
E	package width	6	-	6.1	6.2	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.85	-	0.9	1.05	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	



2. Package outline

TSSOP64: plastic thin shrink small outline package; 64 leads; body width 6.1 mm SOT646-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.27 0.17	0.2 0.1	17.1 16.9	6.2 6.0	0.5	8.3 7.9	1	0.75 0.45	0.2	0.08	0.1	0.89 0.61	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT646-1		MO-153				-00-08-21 03-02-18

Fig. 1. Package outline TSSOP64 (SOT646-1)

### 3. Soldering

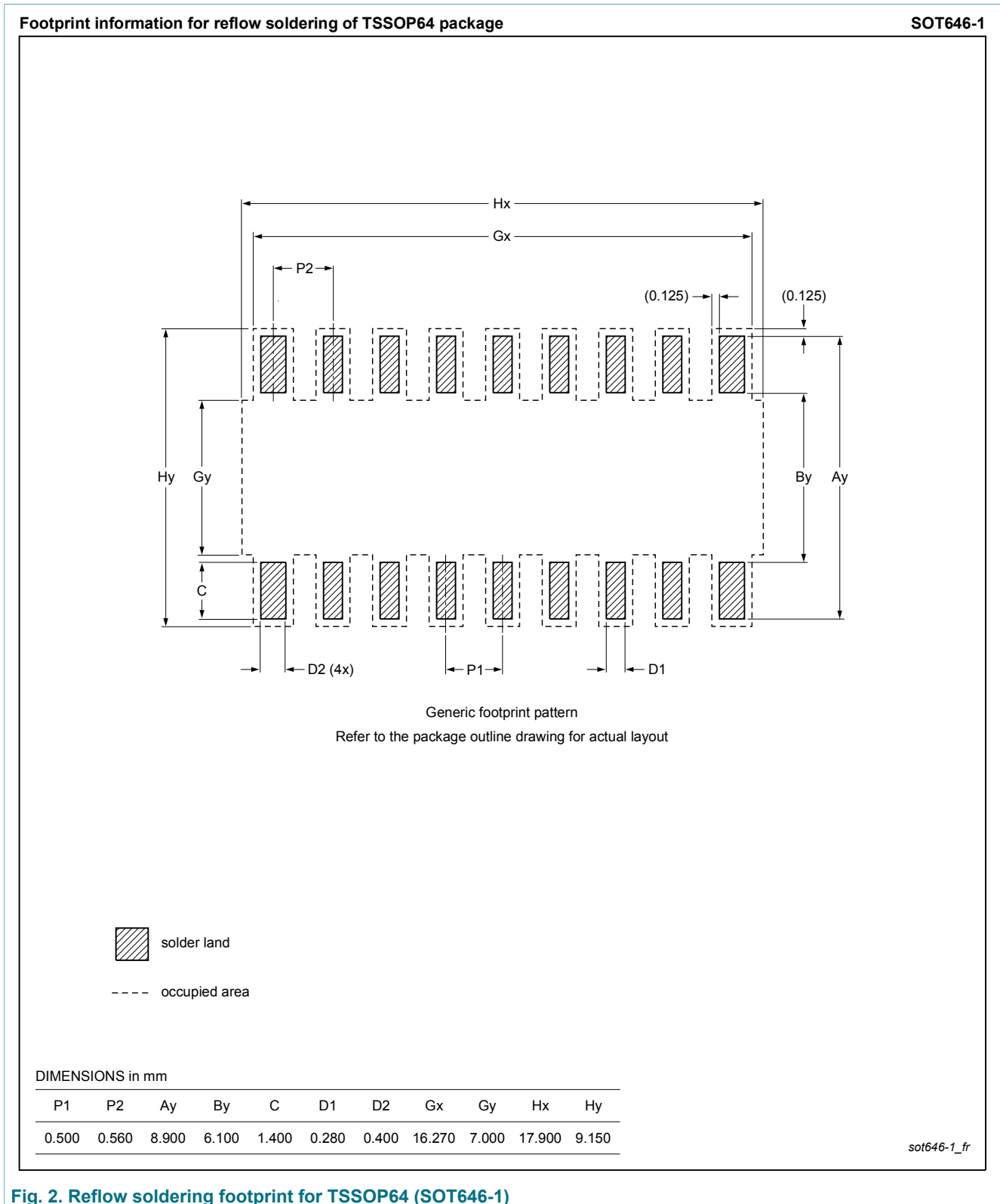


Fig. 2. Reflow soldering footprint for TSSOP64 (SOT646-1)

## 4. Legal information

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